

## Fast Facts

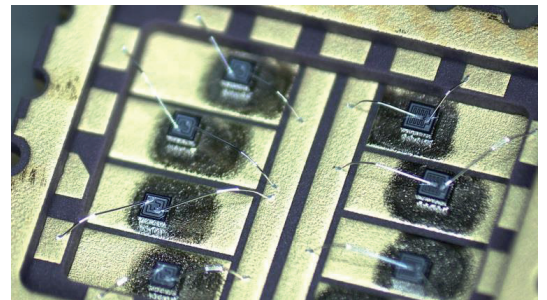
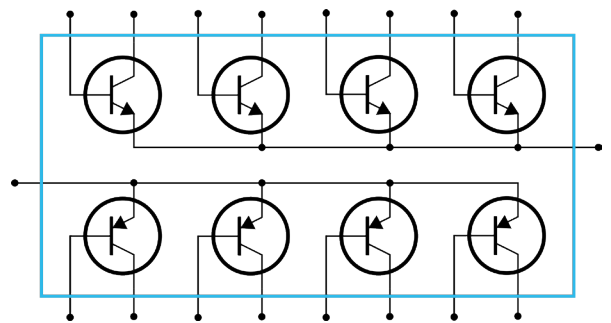
## Conceptual

# Miniaturised Hermetic (Dual Polarity) Multi-Chip Arrays

Through TT Electronics Lutterworth facility, formerly Semelab Limited, TT and ST are proud to announce the collaborative launch of new arrays for both traditional and New Space activity. These combine TT Electronics' state of the art packaging and ST's die/silicon chips with many proven flight hours in the harshest of Space environments.

Over 3500 multi-chip arrays using ST die and TT Electronics packaging have been supplied for the payload of Galileo F.O.C with further parts to be supplied for the final tranche of the constellation. The Galileo array combined power MOSFET's, protection and driver transistors in a custom configuration.

This new array offers the satellite manufacturer the ability to try this unique packaging technology with known performance die in a 4+4 common emitter configuration. Other configurations or full custom design solutions are available on request.



### FEATURES

- PCB real estate saving
- Weight saving
- Increased reliability
- Fully Hermetic - HTCC package
- Grounded package lid to mitigate against deep dielectric discharge
- Screening options available in accordance with ESA, DLA JANS or customer specific 'New Space' quality levels
- Proven technology with over 25 years space heritage
- BJT example shown, MOSFET and other technologies can be substituted

### APPLICATIONS

- Aerospace / Space Communication Systems
- Amplifier Circuits
- Solenoid/Relay Control Circuits
- Motor control systems
- Input bridges
- Switch matrix's